

Description

The IRF8707TRPBF uses advanced trench technology

to provide excellent $R_{\text{DS}(\text{ON})},$ low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

General Features

V_{DS} = 30V I_D =13A

 $R_{DS(ON)} < 13m\Omega @ V_{GS}=10V$

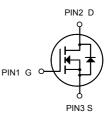
Application

Battery protection

Load switch Uninterruptible power supply



SOP-8



N-Channel MOSFET

Package Marking and Ordering Information

Product ID Pack			Marking Qty(PCS) 4406 XXX YYYY 3000	
			6	
	IRF8707TRPBF	SOP-8	4406 XXX YYYY	3000

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
Vds	Drain-Source Voltage	30	V
Vgs	Gate-Source Voltage	Gate-Source Voltage ±20	
I₀@T _A =25°C	Continuous Drain Current ¹	13	А
ID@TA=70°C	Continuous Drain Current ¹	7	А
Ідм	Pulsed Drain Current ²	41	A
EAS	Single Pulse Avalanche Energy ³	15	mJ
PD@TA=25°C	Total Power Dissipation ⁴	12	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
_	Thermal Resistance Junction-ambient¹(t≤10s)	85	°C/W
R ₀ ja	Thermal Resistance Junction-ambient ¹	25	°C/W



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	30			V	
$\triangle BV_{DSS} / \triangle T_J$	BVDSS Temperature Coefficient	Reference to 25° C , I _D =1mA		0.034		V/°C	
Bacau	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =7A		9.5	13	mΩ	
Rds(on)	Static Drain-Source On-Resistance-	V _{GS} =4.5V , I _D =4A		15	19		
$V_{GS(th)}$	Gate Threshold Voltage		1.2	1.4	2.5	V	
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	—_V _{GS} =V _{DS} , I _D =250uA		-3.84		mV/°C	
	Durin Course Lookage Current	V _{DS} =24V , V _{GS} =0V , T _J =25°C			1		
IDSS	Drain-Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J =55°C			5	uA	
lgss	Gate-Source Leakage Current	V _{GS=} ±20V , V _{DS} =0V			±100	nA	
gfs	Forward Transconductance	V _{DS} =5V , I _D =7A		6.2		S	
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.04	2.1	Ω	
Qg	Total Gate Charge (4.5V)			6	8.4		
Qgs	Gate-Source Charge	V _{DS} =15V , V _{GS} =4.5V , I _D =7A		2.2	3.1	nC	
Q _{gd}	Gate-Drain Charge			2	2.8		
T _{d(on)}	Turn-On Delay Time			1.2	2.4		
Tr	Rise Time	V _{DD} =15V , V _{GS} =10V , R _G =3.3Ω I _D =7A		40	72.0	- ns	
T _{d(off)}	Turn-Off Delay Time			18	36.0		
T _f	Fall Time			7.2	14.4		
Ciss	Input Capacitance			783	1316		
Coss	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		127	167.8	pF	
Crss	Reverse Transfer Capacitance			89	122.6	1	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
ls	Continuous Source Current ^{1,5}	V _G =V _D =0V , Force Current			7	А
I _{SM}	Pulsed Source Current ^{2,5}	VG-VD-UV, FOICe Cullent			35	А
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	V
trr	Reverse Recovery Time			7.2		nS
Qrr	Reverse Recovery Charge	I⊧=7A , dI/dt=100A/µs , Tյ=25°C		2.9		nC

Note :

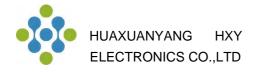
1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width $\,\leq\,$ 300us , duty cycle $\,\leq\,$ 2%

3. The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V, L=0.1mH, I_{AS} =20A

4. The power dissipation is limited by 150°C junction temperature

5. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



IRF8707TRPBF N-Channel Enhancement Mode MOSFET

Typical Characteristics

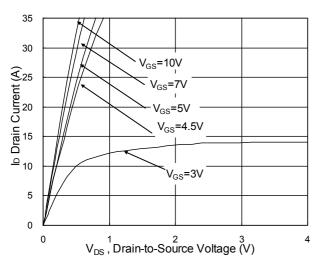


Fig.1 Typical Output Characteristics

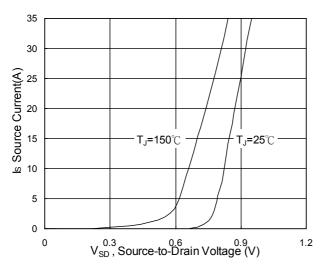


Fig.3 Forward Characteristics Of Reverse

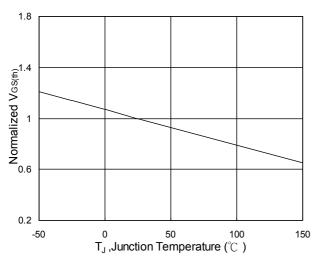


Fig.5 Normalized $V_{\text{GS}(\text{th})}$ vs. T_{J}

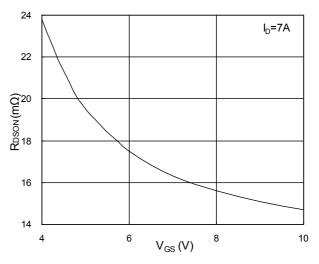


Fig.2 On-Resistance vs. Gate-Source

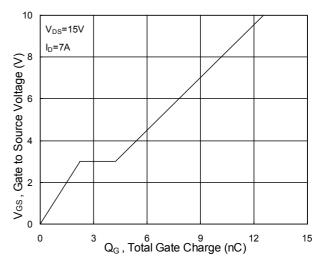


Fig.4 Gate-Charge Characteristics

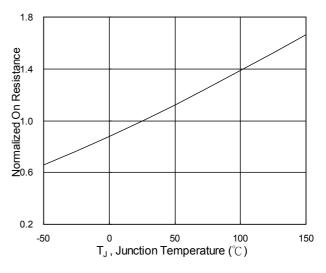
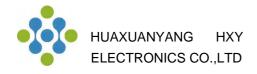


Fig.6 Normalized R_{DSON} vs. T_J



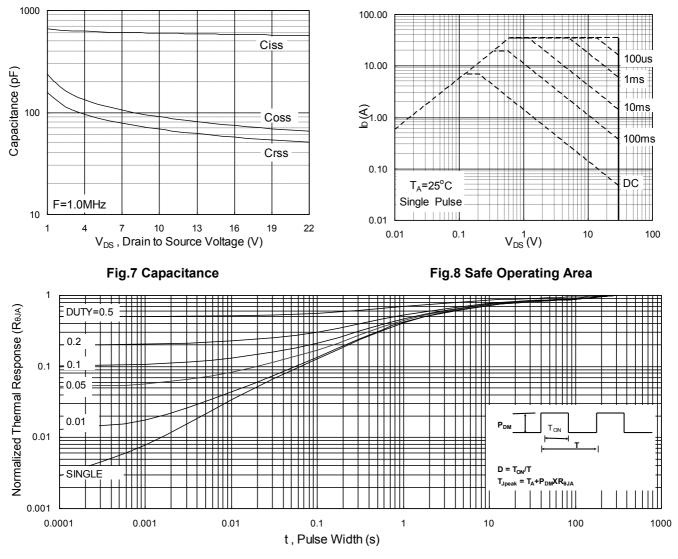


Fig.9 Normalized Maximum Transient Thermal Impedance

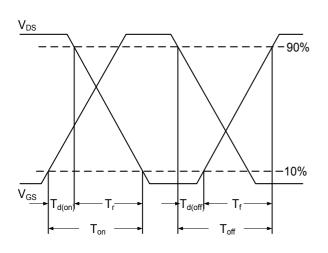


Fig.10 Switching Time Waveform

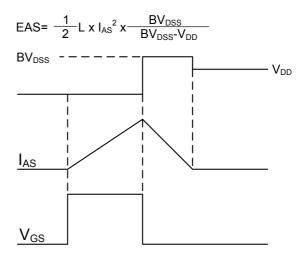
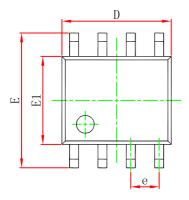
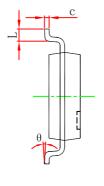


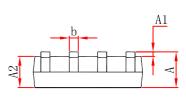
Fig.11 Unclamped Inductive Switching Waveform



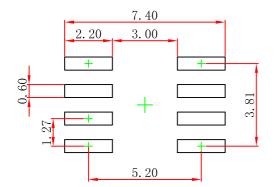
SOP-8 Package Outline Dimensions







Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
с	0.170	0.250	0.007	0.010	
D	4.800	5.000	0.189	0.197	
e	1.270 (1.270 (BSC)		(BSC)	
E	5.800	6.200	0.228	0.244	
E1	3.800	4.000	0.150	0.157	
L	0.400	1.270	0.016	0.050	
θ	0 °	8°	0 °	8°	



Note: 1.Controlling dimension: in millimeters.

2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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